

L Number	Hits	Search Text	DB	Time stamp
-	707	257/758 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/07 10:21
-	28	257/639 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/18 17:25
-	76	257/640 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:12
-	31	257/641 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:13
-	60	257/642 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:18
-	44	257/643 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:19
-	38	257/644 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:22
-	66	257/324 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:25
-	110	257/635 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:30
-	176	257/759 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/21 10:13
-	223	257/760 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 15:47
-	619	438/624 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 16:02
-	298	438/623 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/20 16:09
-	98	438/761 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/21 09:56

-	649	438/622 and ((metal adj lines) or (conductive adj layers)) and (dielectric adj layers) and (contact or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/21 07:29
-	191	257/758 and interlayer and (metal adj layers) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/04 15:29
-	30	257/759 and interlayer and (metal adj layers) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 14:05
-	56	257/760 and interlayer and (metal adj layers) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/04 18:10
-	3	(conductive adj layer) and (insulating adj interlayer) and electrode and (transmission adj line)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 14:08
-	171	(conductive adj layer) and (insulating adj interlayer) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/07 15:07
-	153	(wiring adj layer) and (insulating adj interlayer) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 18:23
-	4	257/211 and (wiring adj layer) and (insulating adj interlayer) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 18:29
-	2	257/635 and (wiring adj layer) and (insulating adj interlayer) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 18:30
-	1	257/728 and (wiring adj layer) and (insulating adj interlayer) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 18:31
-	8	257/758 and (wiring adj layer) and (insulating adj interlayer) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/07 08:24
-	5	438/624 and (wiring adj layer) and (insulating adj interlayer) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/07 08:35
-	53	438/\$.ccls. and (wiring adj layer) and (insulating adj interlayer) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/07 09:02
-	105	257/\$.ccls. and (wiring adj layer) and (insulating adj interlayer) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/07 10:04

	24	257/\$.ccls. and (wiring adj layer) and (insulating adj interlayer) and electrode and (ground or (ground adj plate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/07 10:06
	195	257/662	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/07 15:17
	641	257/664	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/07 16:09
	1011	(transmission adj line) and ground and ((multilayer adj wiring) or conduct\$4) and cross and electrode and (high adj frequency)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 13:37
	383	(transmission adj line) same ground same ((multilayer adj wiring) or conduct\$4) same electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 13:16
	172	257/\$.ccls. and (transmission adj line) and ground and ((multilayer adj wiring) or conduct\$4) and cross and electrode and (high adj frequency)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 13:59
	48	438/\$.ccls. and (transmission adj line) and ground and ((multilayer adj wiring) or conduct\$4) and cross and electrode and (high adj frequency)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/08 14:01
	88	257/752 and (dielectric adj layers) and ((stop adj layer) or (etch adj stop)) and (via or contact) and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/02 11:01
	360	257/758 and ((metal adj layers) or (conductive adj layers)) and (dielectric adj layers) and (contact or via) and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/19 15:19
	98	257/759 and ((metal adj layers) or (conductive adj layers)) and (dielectric adj layers) and (contact or via) and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/19 14:41
	111	257/760 and ((metal adj layers) or (conductive adj layers)) and (dielectric adj layers) and (contact or via) and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/19 10:25
	23	257/324 and ((metal adj layers) or (conductive adj layers)) and (dielectric adj layers) and (contact or via) and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/19 10:35
	15	257/637 and ((metal adj layers) or (conductive adj layers)) and (dielectric adj layers) and (contact or via) and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/19 10:36
	41	257/642 and ((metal adj layers) or (conductive adj layers)) and (dielectric adj layers) and (contact or via) and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/19 10:42

-	444	438/622 and ((metal adj layers) or (conductive adj layers)) and (dielectric adj layers) and (contact or via) and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/19 11:10
-	185	438/623 and ((metal adj layers) or (conductive adj layers)) and (dielectric adj layers) and (contact or via) and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/19 11:21
-	380	438/624 and ((metal adj layers) or (conductive adj layers)) and (dielectric adj layers) and (contact or via) and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/19 11:48
-	98	438/619 and ((metal adj layers) or (conductive adj layers)) and (dielectric adj layers) and (contact or via) and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/19 12:58
-	554	438/637 and ((metal adj layers) or (conductive adj layers)) and (dielectric adj layers) and (contact or via) and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/14 13:24
-	88	257/259	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/14 13:46
-	207	257/662	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/14 17:12
-	672	257/664	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/15 08:36
-	1652	257/691	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/15 09:31
-	936	257/728	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/15 10:17
-	1998	257/698	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/15 11:04
-	299	438/167	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/15 11:13
-	130	438/186	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/15 17:51
-	315	257/275	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/15 17:51

-	79	257/275 and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 18:30
-	46	257/276 and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 18:33
-	66	333/104 and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 18:35
-	63	333/161 and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 18:38
-	95	333/204 and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 07:58
-	91	333/238 and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 08:37
-	221	333/246 and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 11:52
-	18	MMIC and transmission and stripline and (ground or (ground adj plane)) and (cross adj over)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 10:38